Product/Process Change Notice - PCN 16_0027 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title:	Assembly Site Transfer of Select CSP_BGA Products to STATS ChipPAC Korea
Publication Date:	30-Mar-2016
Effectivity Date:	01-Oct-2016 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Removed parts. Added parts. Revised attachment - Part list with BOM changes
Revised the attachment - Qual plan summary for CSP_BGA parts

Description Of Change

ADI is transferring to subcontractor STATS ChipPAC Korea for the assembly manufacturing of select CSP_BGA products. The package outline dimensions of each product will be maintained. The die attach material and mold compound material of the select CSP_BGA products will be changed, see attached part list for details.

Reason For Change

ADI is transferring to STATS ChipPAC Korea for assembly manufacturing, due to the closure of STATS ChipPAC China at the end of 2017. ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled from alternate Assembly site will be identified by
assembly lot and the country of origin.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: **Type**: Qualification Plan

ADI_PCN_16_0027_Rev_A_Qual Plan Summary CSP_BGA.pdf

Attachment 2: **Type**: Detailed Parts List

ADI_PCN_16_0027_Rev_A_Part List with BOM change.xlsx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (10)

ADAS1131 / ADAS1131JBCZ	ADAS1135 / ADAS1135JBCZ	ADUCM310 / ADUCM310BBCZ	ADUCM310 / ADUCM310BBCZ-RL	ADUCM320 / ADUCM320BBCZ-RL
ADUCM320 / ADUCM320BBCZI-RL	ADUCM322 / ADUCM322BBCZ	ADUCM322 / ADUCM322BBCZ-RL	ADUCM322 / ADUCM322BBCZI	ADUCM322 / ADUCM322BBCZI-RL

Added Parts On This Revision - Product Family / Model Number (2)

ADUCM320 / ADUCM320BBCZ	ADUCM320 / ADUCM320BBCZI			

Removed Parts On All Revisions - Product Family / Model Number (2)

ADDI9009 / ADDI9009BBCZ	ADDI9009 / ADDI9009BBCZRL			

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	07-Mar-2016	01-Jul-2016	Initial Release
Rev. A	30-Mar-2016	01-Oct-2016	Removed parts. Added parts. Revised attachment - Part list with BOM changes Revised the attachment - Qual plan summary for CSP_BGA parts